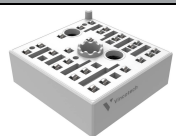
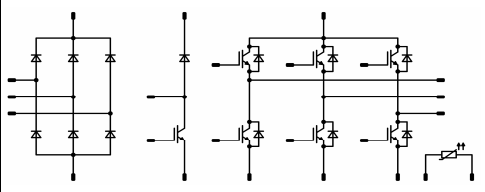




Vincotech

MiniSKiiP® 1 PIM	1200 V / 15 A
<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;">Features</div> <ul style="list-style-type: none"> Solderless interconnection Trench Fieldstop IGBT4 technology 	<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;">MiniSKiiP® 1 housing</div> 
<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;">Target Applications</div> <ul style="list-style-type: none"> Industrial drives 	<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;">Schematic</div> 
<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;">Types</div> <ul style="list-style-type: none"> V23990-K200-A40-PM 	

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Rectifier Diode				
Repetitive peak reverse voltage	V_{RRM}		1600	V
DC forward current	I_{FAV}		25	A
Surge (non-repetitive) forward current	I_{FSM}	$t_p = 10\text{ ms}$ half sine	220	A
I^2t -value	I^2t		200	A ² s
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	51	W
Maximum Junction Temperature	T_{jmax}		150	°C
Inverter Switch / Brake Switch				
Collector-emitter breakdown voltage	V_{CE}		1200	V
DC collector current	I_C		15	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	45	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	88	W
Gate-emitter peak voltage	V_{GE}		±20	V
Short circuit ratings	t_{SC}	$T_j \leq 150\text{ °C}$ $V_{GE} = 15\text{ V}$, $V_{CC} = 800\text{ V}$	10	µs
Maximum Junction Temperature	T_{jmax}		175	°C
Inverter Diode / Brake Diode				
Repetitive peak reverse voltage	V_{RRM}		1200	V
DC forward current	I_F		15	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	66	W
Maximum Junction Temperature	T_{jmax}		175	°C



Maximum Ratings

$T_i = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Thermal Properties				
Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{op}		-40...+($T_{jmax} - 25$)	°C
Isolation Properties				
Isolation voltage	V_{is}	$t = 2\text{ s}$ DC Test Voltage*	5500	V
		$t = 1\text{ min}$ AC Voltage	2500	V
Creepage distance		With std lid For more information see handling instructions	6,3	mm
Clearance		With std lid For more information see handling instructions	6,3	mm
Comparative Tracking Index	CTI		>200	

* 100 % tested in production



Characteristic Values

Parameter	Symbol	Conditions					Value			Unit	
		V_{GE} [V]	V_{GS} [V]	V_r [V]	V_{CE} [V]	V_{DS} [V]	I_C [A]	I_F [A]	I_D [A]		T_j [°C]

Rectifier Diode

Forward voltage	V_F					25	25 125			1,51 1,42			V
Threshold voltage (for power loss calc. only)	V_{to}					25	25 125			0,86 0,79			V
Slope resistance (for power loss calc. only)	r_t					25	25 125			0,03 0,03			Ω
Reverse current	I_r					1500			25			0,05	mA
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 2,5 \text{ W/mK}$ (HPTP)										1,37	K/W

Inverter Switch / Brake Switch

Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$				0,0005	25			5,3	5,8	6,3	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15			15	25 150			1,6	2,2 2,48	2,4	V
Collector-emitter cut-off current incl. Diode	I_{CES}		0	1200			25					0,06	mA
Gate-emitter leakage current	I_{GES}		20	0			25					180	nA
Integrated Gate resistor	R_{gint}										none		Ω
Turn-on delay time	$t_{d(on)}$	$R_{goff} = 32 \Omega$ $R_{gon} = 32 \Omega$	± 15	600	15		25					102	ns
Rise time	t_r						150				33		
Turn-off delay time	$t_{d(off)}$						25				37		
Fall time	t_f						150				216		
Turn-on energy loss	E_{on}						25				284		
Turn-off energy loss	E_{off}						150				90	mWs	
Input capacitance	C_{ies}	25				1,53							
Reverse transfer capacitance	C_{rss}	$f = 1 \text{ MHz}$	0	25		25					890	pF	
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 2,5 \text{ W/mK}$ (HPTP)										1,08	K/W

Inverter Diode / Brake Diode

Diode forward voltage	V_F					15	25 150			1,6	2,6 2,64	2,9	V	
Peak reverse recovery current	I_{RRM}	$R_{goff} = 32 \Omega$	± 15	600	15		25						7,78	A
Reverse recovery time	t_{rr}						150				10,8			
Reverse recovered charge	Q_{rr}						25				299	ns		
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$						150				541			
Reverse recovered energy	E_{rec}						25				0,98	mWs		
Thermal resistance junction to sink	$R_{th(j-s)}$						150				2,33			
						25						0,38	K/W	
						150						0,97		

Thermistor

Rated resistance	R					25					1000		Ω
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1670 \Omega$				100				-2		2	%
R_{100}	R					100					1670		Ω
Power dissipation constant						25					0,76		mW/K
A-value	$B_{(25/50)}$					25					$7,635 \cdot 10^{-3}$		1/K
B-value	$B_{(25/100)}$					25					$1,731 \cdot 10^{-5}$		1/K ²
Vincotech NTC Reference												E	



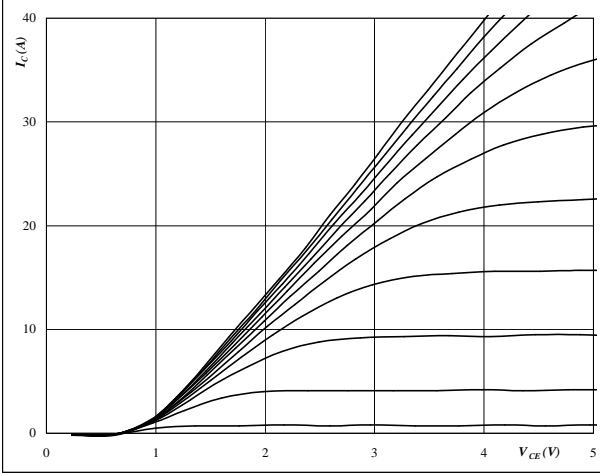
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 1. IGBT

Typical output characteristics

$I_C = f(V_{CE})$



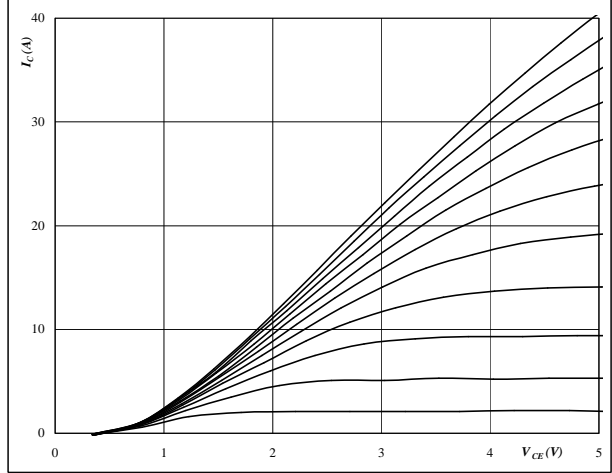
At

$t_p = 250 \mu s$
 $T_j = 25 \text{ }^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 2. IGBT

Typical output characteristics

$I_C = f(V_{CE})$



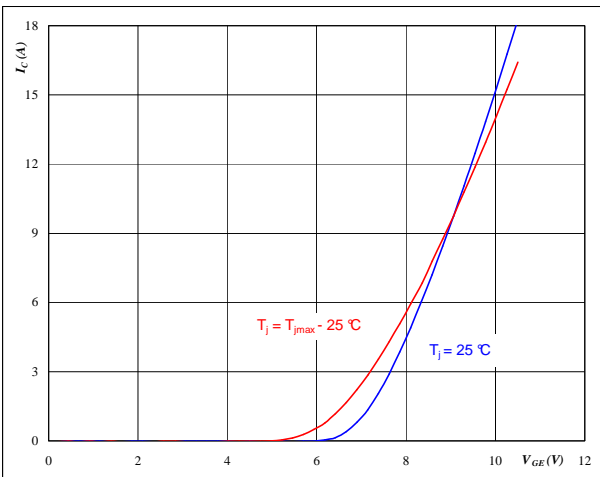
At

$t_p = 250 \mu s$
 $T_j = 150 \text{ }^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$



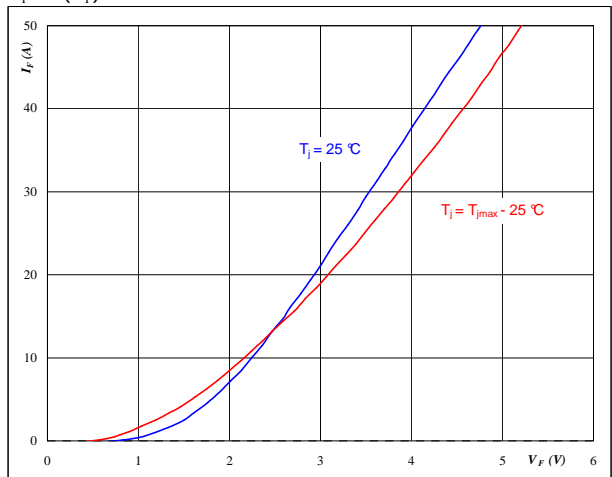
At

$t_p = 250 \mu s$
 $V_{CE} = 10 V$

figure 4. FWD

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



At

$t_p = 250 \mu s$



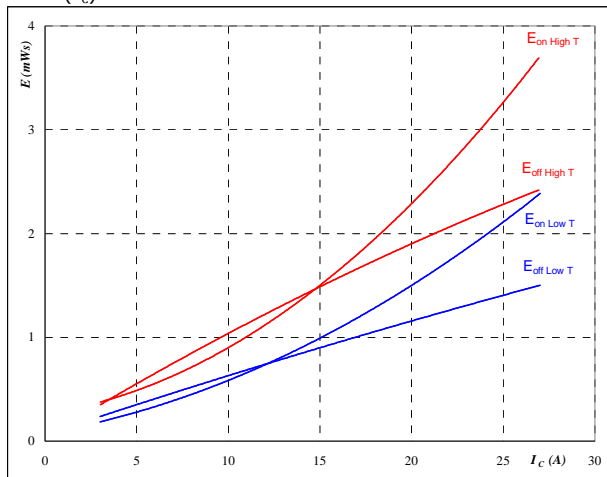
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 5. IGBT

Typical switching energy losses
as a function of collector current

$$E = f(I_C)$$



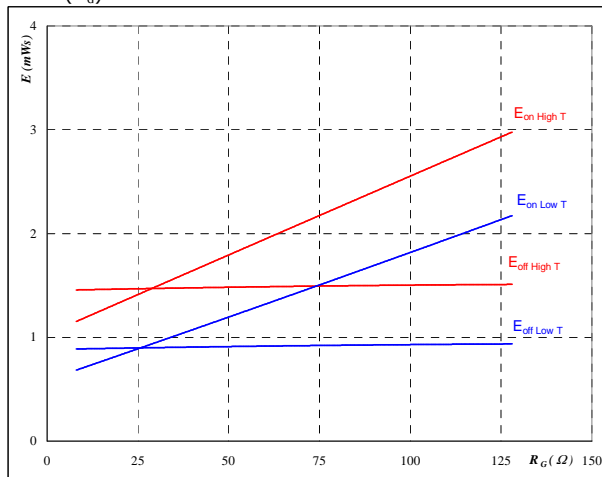
With an inductive load at

$T_j = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 32$ Ω
 $R_{goff} = 32$ Ω

figure 6. IGBT

Typical switching energy losses
as a function of gate resistor

$$E = f(R_G)$$



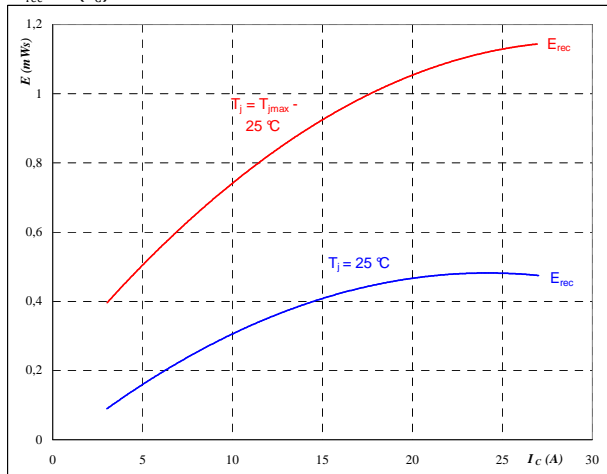
With an inductive load at

$T_j = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 15$ A

figure 7. FWD

Typical reverse recovery energy loss
as a function of collector current

$$E_{rec} = f(I_C)$$



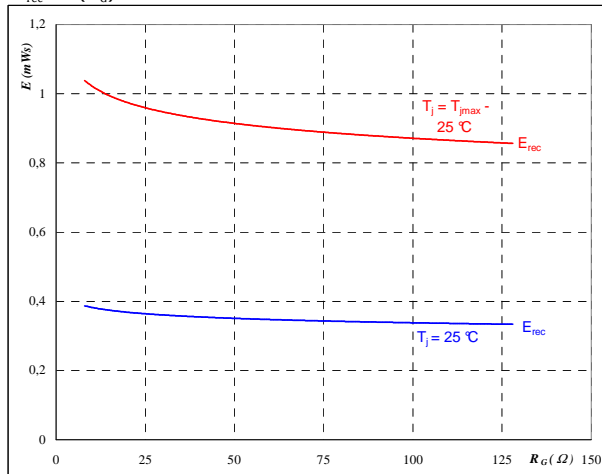
With an inductive load at

$T_j = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 32$ Ω

figure 8. IGBT

Typical reverse recovery energy loss
as a function of gate resistor

$$E_{rec} = f(R_G)$$



With an inductive load at

$T_j = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 15$ A



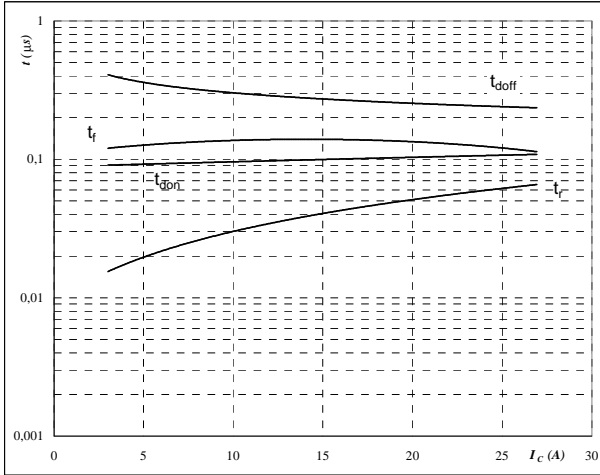
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 9. IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



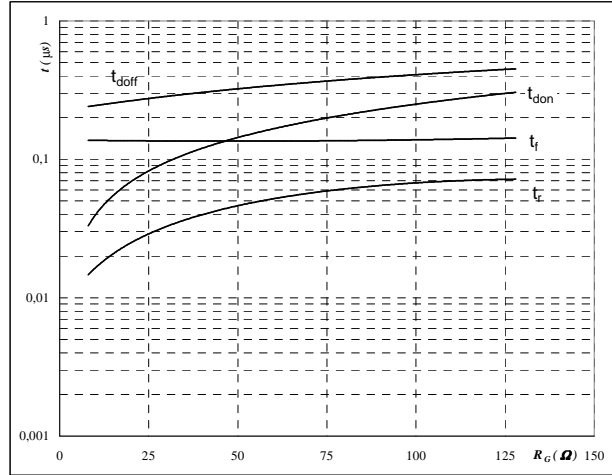
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	32	Ω
$R_{goff} =$	32	Ω

figure 10. IGBT

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



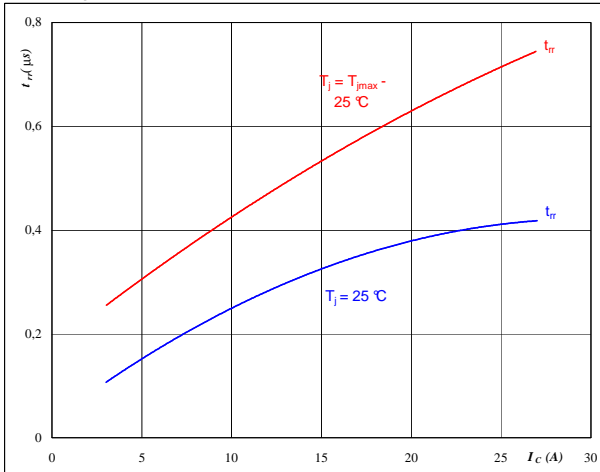
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	15	A

figure 11. FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_C)$$



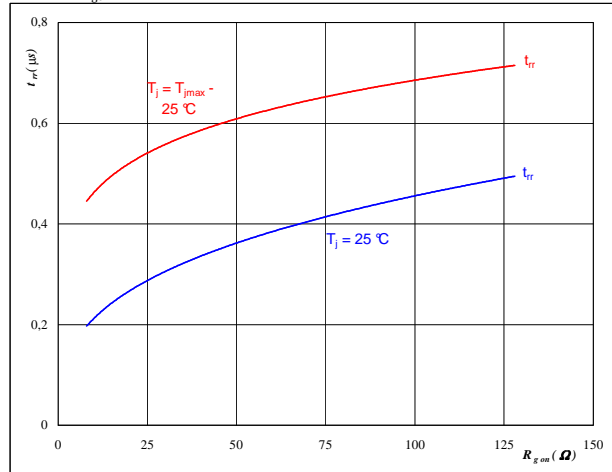
At

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	32	Ω

figure 12. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At

$T_j =$	25/150	°C
$V_R =$	600	V
$I_F =$	15	A
$V_{GE} =$	±15	V



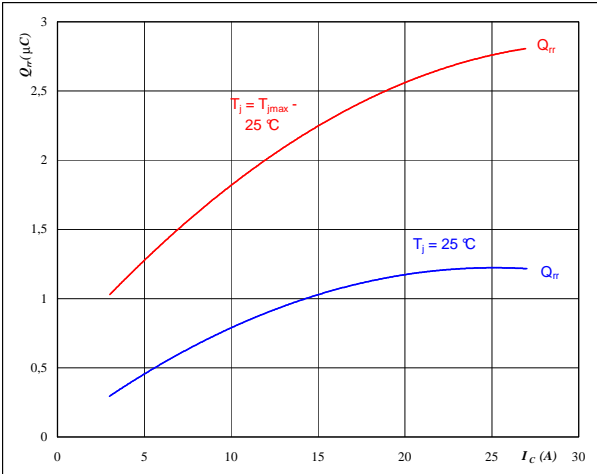
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 13. FWD

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_c)$$



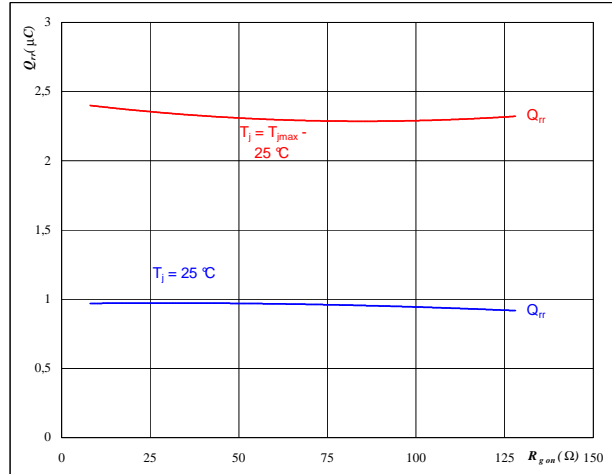
At

$T_j = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 32$ Ω

figure 14. FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$



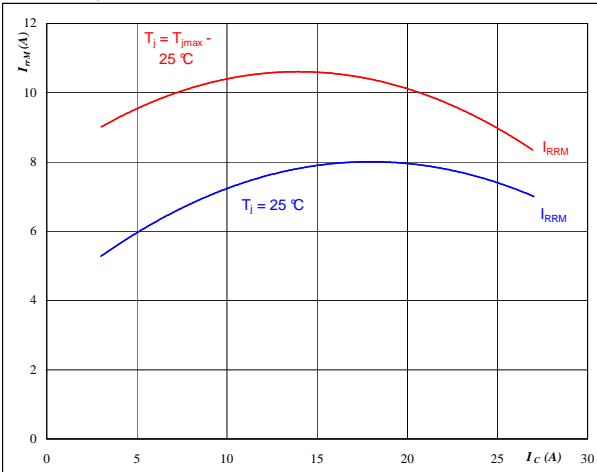
At

$T_j = 25/150$ °C
 $V_R = 600$ V
 $I_F = 15$ A
 $V_{GE} = \pm 15$ V

figure 15. FWD

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_c)$$



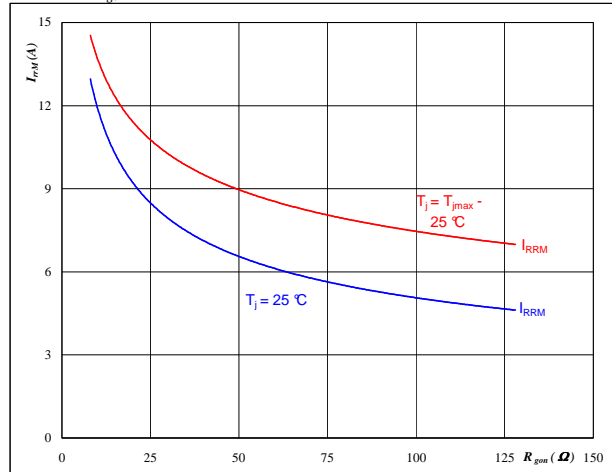
At

$T_j = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 32$ Ω

figure 16. FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$



At

$T_j = 25/150$ °C
 $V_R = 600$ V
 $I_F = 15$ A
 $V_{GE} = \pm 15$ V



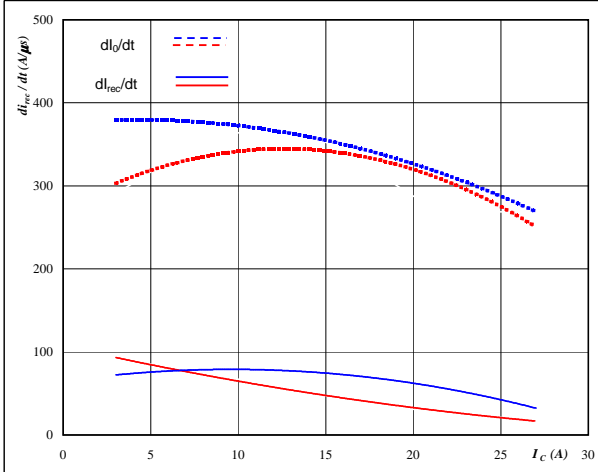
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 17. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$$dI_0/dt, dI_{rec}/dt = f(I_C)$$

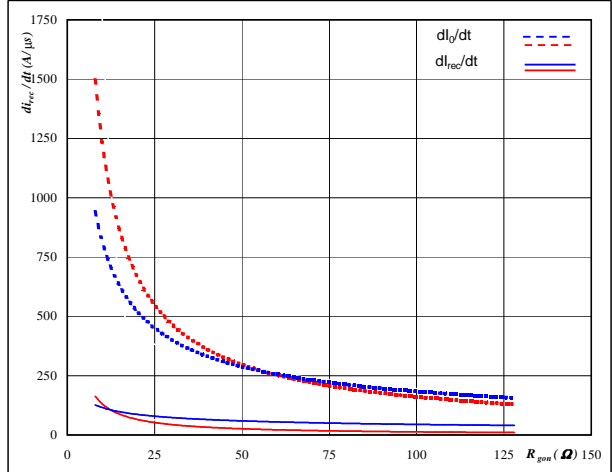


At
 $T_j = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 32$ Ω

figure 18. FWD

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$$dI_0/dt, dI_{rec}/dt = f(R_{gon})$$

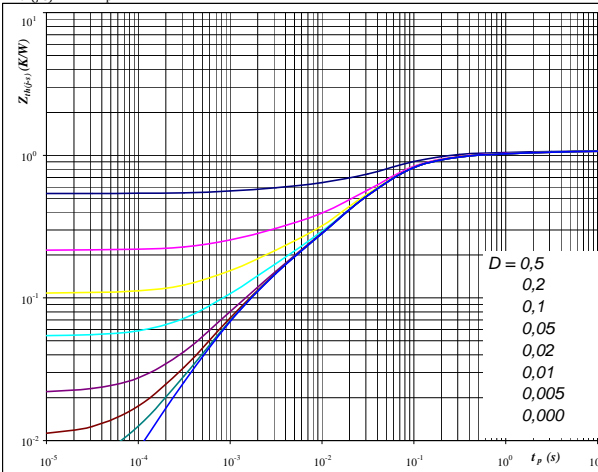


At
 $T_j = 25/150$ °C
 $V_R = 600$ V
 $I_F = 15$ A
 $V_{GE} = \pm 15$ V

figure 19. IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At
 $D = t_p / T$
 $R_{th(j-s)} = 1,08$ K/W

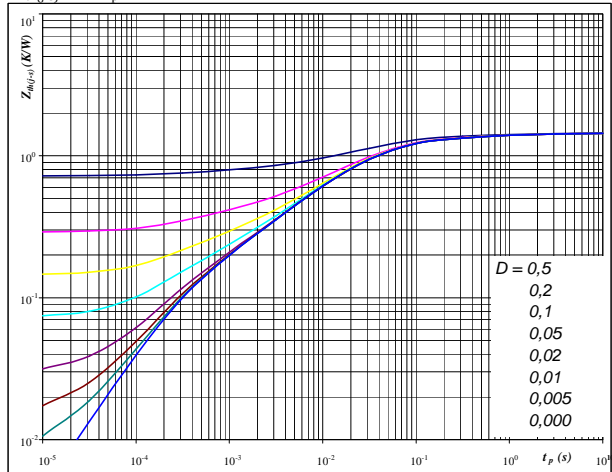
IGBT thermal model values

R (K/W)	Tau (s)
4,02E-02	8,05E+00
7,53E-02	6,86E-01
2,00E-01	1,22E-01
5,79E-01	4,09E-02
1,08E-01	7,96E-03
7,24E-02	1,22E-03
4,99E-03	5,90E-04

figure 20. FWD

FWD transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At
 $D = t_p / T$
 $R_{th(j-s)} = 1,44$ K/W

FWD thermal model values

R (K/W)	Tau (s)
6,32E-02	2,64E+00
1,25E-01	3,53E-01
4,72E-01	5,08E-02
4,73E-01	1,56E-02
2,06E-01	2,93E-03
1,06E-01	3,09E-04



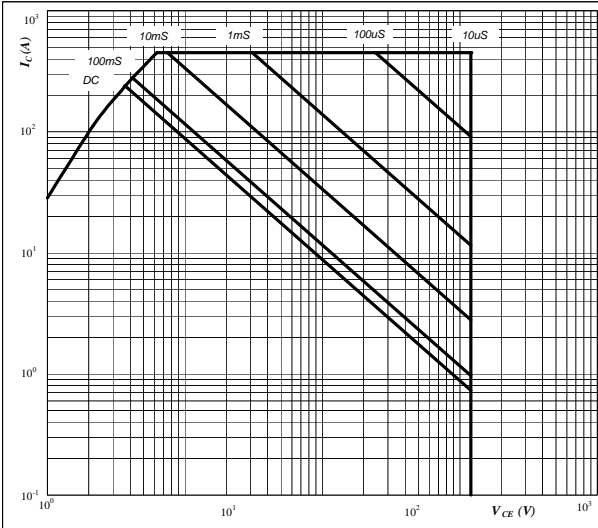
Vincotech

Inverter Switch / Brake Switch / Inverter Diode / Brake Diode

figure 25. IGBT

**Safe operating area as a function
of collector-emitter voltage**

$$I_C = f(V_{CE})$$



At

- $D =$ single pulse
- $T_s = 80$ °C
- $V_{GE} = \pm 15$ V
- $T_j = T_{jmax}$

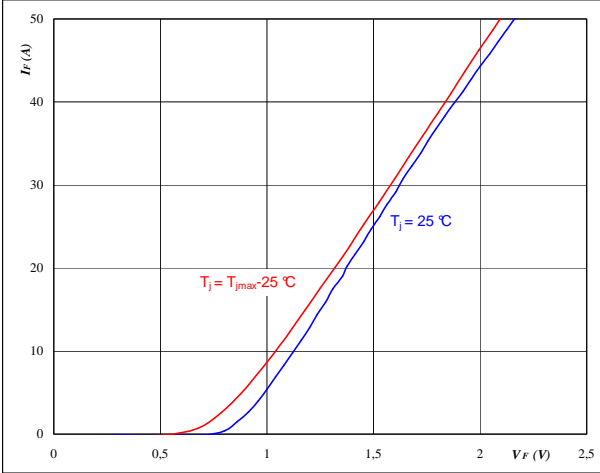


Rectifier Diode

figure 1. Diode

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$



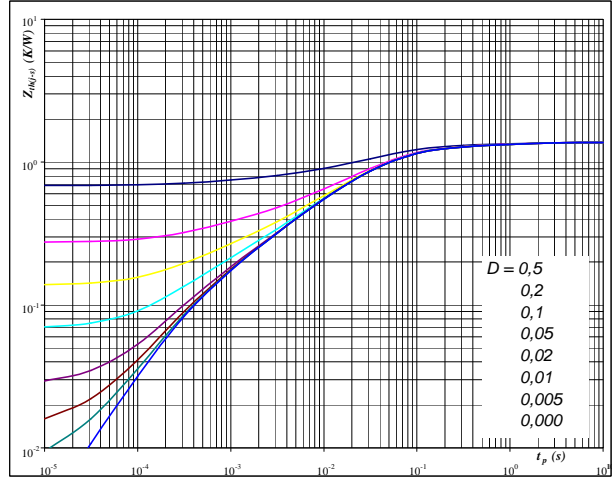
At

$$t_p = 250 \mu\text{s}$$

figure 2. Diode

Diode transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At

$$D = t_p / T$$

$$R_{th(j-s)} = 1,37 \text{ K/W}$$

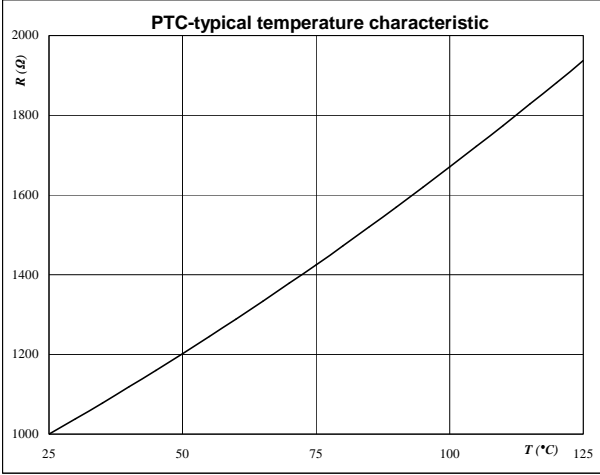


Thermistor

figure 1. Thermistor

**Typical PTC characteristic
as a function of temperature**

$$R = f(T)$$





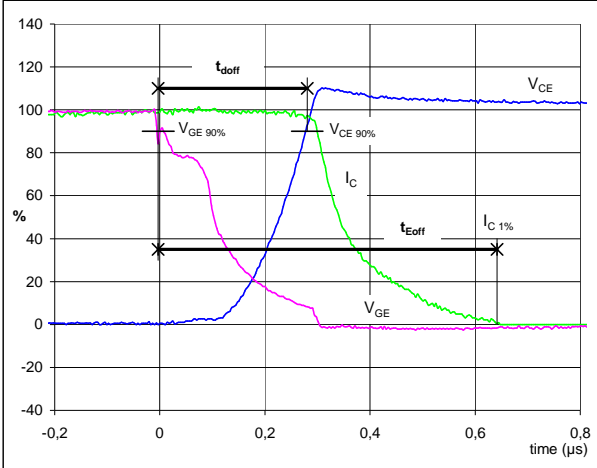
Switching Definitions

General conditions

T_j	=	150 °C
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

figure 1. IGBT

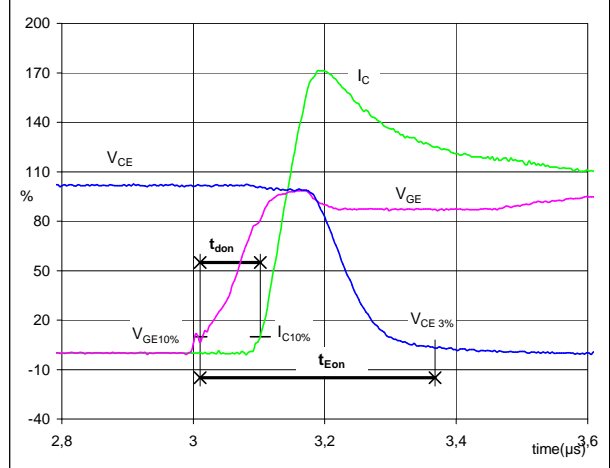
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
(t_{Eoff} = integrating time for E_{off})



V_{GE} (0%) =	-15	V
V_{GE} (100%) =	15	V
V_C (100%) =	600	V
I_C (100%) =	15	A
t_{doff} =	0,28	μ s
t_{Eoff} =	0,64	μ s

figure 2. IGBT

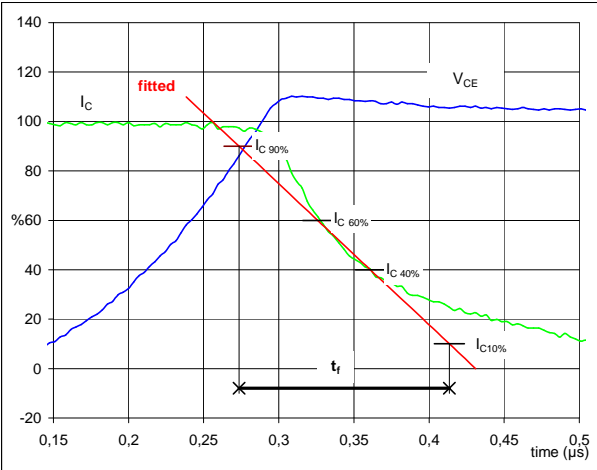
Turn-on Switching Waveforms & definition of t_{donr} , t_{Eon}
(t_{Eon} = integrating time for E_{on})



V_{GE} (0%) =	-15	V
V_{GE} (100%) =	15	V
V_C (100%) =	600	V
I_C (100%) =	15	A
t_{don} =	0,10	μ s
t_{Eon} =	0,36	μ s

figure 3. IGBT

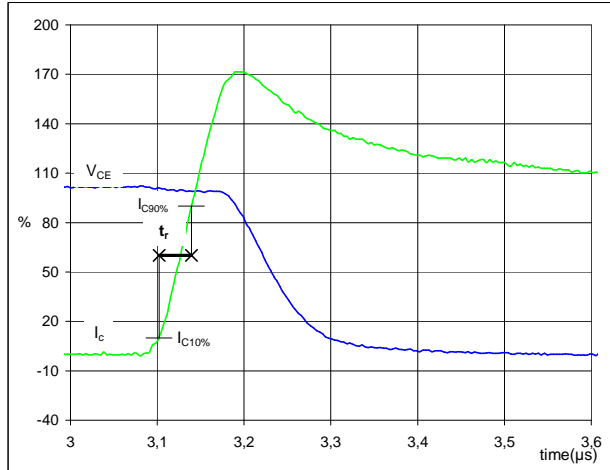
Turn-off Switching Waveforms & definition of t_f



V_C (100%) =	600	V
I_C (100%) =	15	A
t_f =	0,13	μ s

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

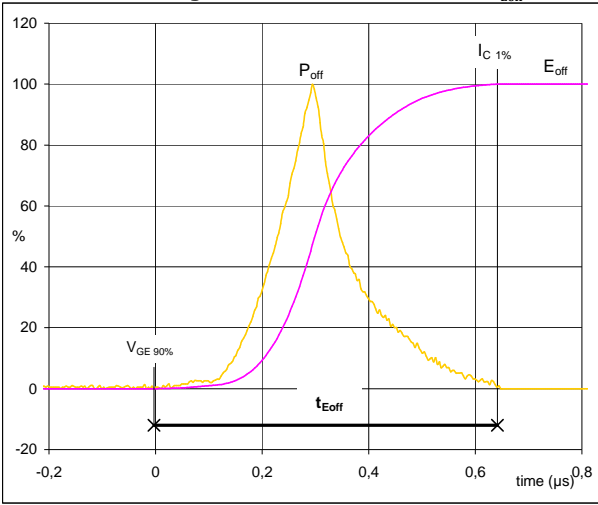


V_C (100%) =	600	V
I_C (100%) =	15	A
t_r =	0,04	μ s



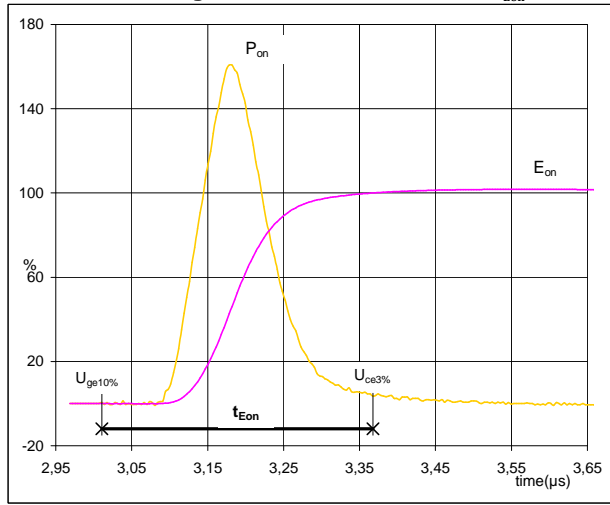
Switching Definitions

figure 5. IGBT
Turn-off Switching Waveforms & definition of t_{Eoff}



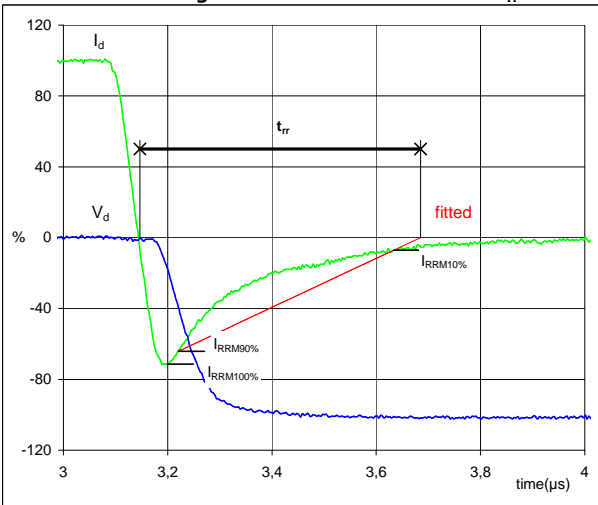
$P_{off} (100\%) = 9,05 \text{ kW}$
 $E_{off} (100\%) = 1,47 \text{ mJ}$
 $t_{Eoff} = 0,64 \text{ μs}$

figure 6. IGBT
Turn-on Switching Waveforms & definition of t_{Eon}



$P_{on} (100\%) = 9,05 \text{ kW}$
 $E_{on} (100\%) = 1,53 \text{ mJ}$
 $t_{Eon} = 0,36 \text{ μs}$

figure 7. FWD
Turn-off Switching Waveforms & definition of t_{rr}



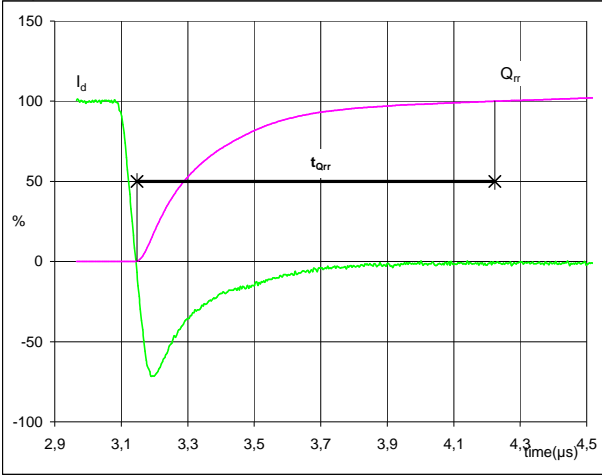
$V_d (100\%) = 600 \text{ V}$
 $I_d (100\%) = 15 \text{ A}$
 $I_{RRM} (100\%) = -11 \text{ A}$
 $t_{rr} = 0,54 \text{ μs}$



Switching Definitions

figure 8. FWD

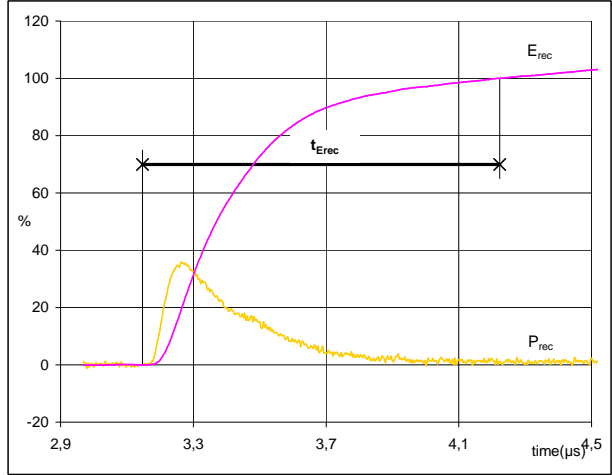
Turn-on Switching Waveforms & definition of t_{Qrr}
(t_{Qrr} = integrating time for Q_{rr})



I_d (100%) =	15	A
Q_{rr} (100%) =	2,33	μC
t_{Qrr} =	1,08	μs

figure 9. FWD

Turn-on Switching Waveforms & definition of t_{Erec}
(t_{Erec} = integrating time for E_{rec})



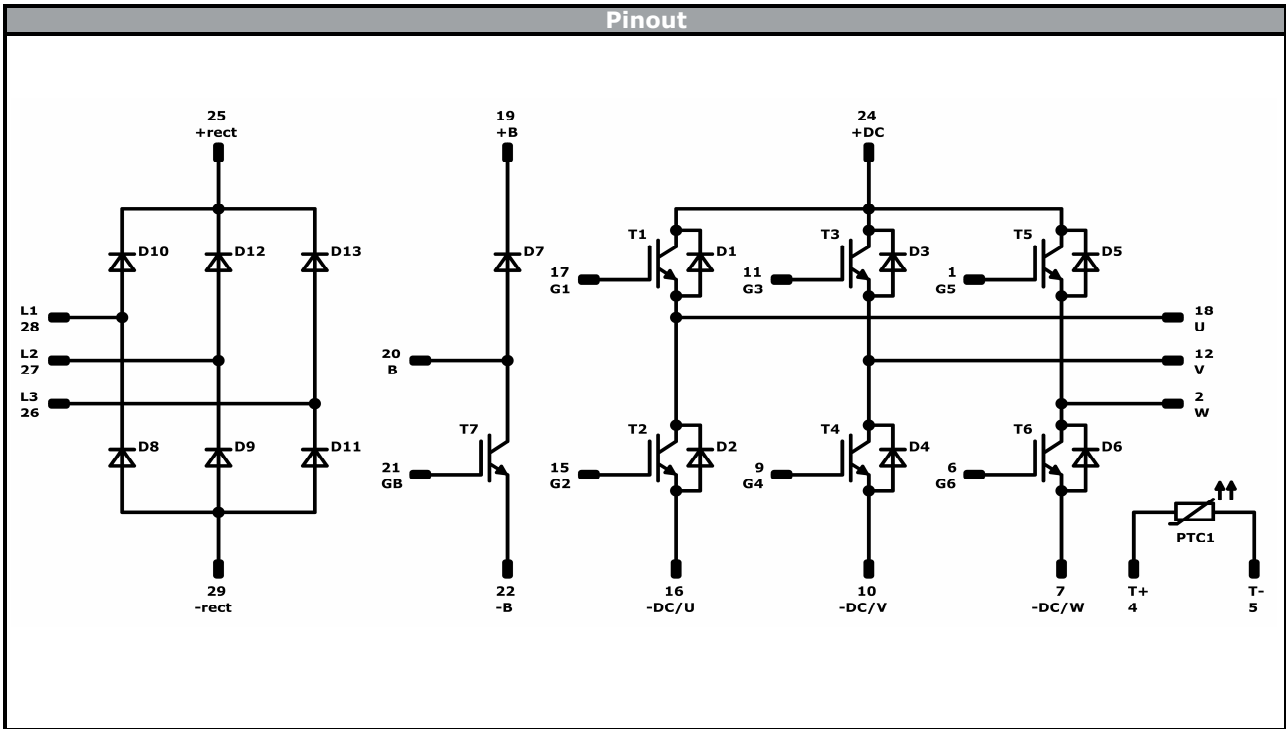
P_{rec} (100%) =	9,05	kW
E_{rec} (100%) =	0,97	mJ
t_{Erec} =	1,08	μs



Ordering Code & Marking									
Version			Ordering Code						
With std lid (6.5mm height) + no thermal grease			V23990-K200-A40-/0A/-PM						
With thin lid (2.8mm height) + no thermal grease			V23990-K200-A40-/0B/-PM						
With std lid (6.5mm height) + thermal grease (0,8 W/mK, P12, silicone-based)			V23990-K200-A40-/1A/-PM						
With thin lid (2.8mm height) + thermal grease (0,8 W/mK, P12, silicone-based)			V23990-K200-A40-/1B/-PM						
With std lid (6.5mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)			V23990-K200-A40-/4A/-PM						
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)			V23990-K200-A40-/4B/-PM						
With std lid (6.5mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)			V23990-K200-A40-/5A/-PM						
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)			V23990-K200-A40-/5B/-PM						
VIN WWWW NNNNNNVV UL LLLL SSSS			Text	VIN	Date code	Name&Ver	UL	Lot	Serial
				VIN	WWYY	NNNNNVV	UL	LLLL	SSSS
			Datamatrix	Type&Ver	Lot number	Serial	Date code		
				TTTTTIV	LLLLL	SSSS	WWYY		

Pad table [mm]			
Pad	X	Y	Function
1	15,93	-14,6	G5
2	15,93	-9,8	W
3	Not assembled		
4	15,93	-0,2	+T
5	15,93	7,62	-T
6	15,93	12,62	G6
7	15,93	15,8	-DC/W
8	Not assembled		
9	8,23	12,62	G4
10	8,23	15,8	-DC/V
11	7,73	-14,6	G3
12	7,73	-9,8	V
13	Not assembled		
14	Not assembled		
15	0,53	12,62	G2
16	0,53	15,8	-DC/U
17	-0,47	-14,6	G1
18	-0,47	-9,8	U
19	-5,47	-5	+B
20	-5,47	5,35	B
21	-7,17	12,62	GB
22	-7,17	15,8	-B
23	Not assembled		
24	-8,07	-9,8	+DC
25	-15,02	-15,8	+RECT
26	-15,02	-9,8	L3
27	-15,02	0	L2
28	-15,02	9,8	L1
29	-15,02	15,8	-RECT

Pad positions refers to center point. For more informations on pad design please see package data.




Identification					
ID	Component	Voltage	Current	Function	Comment
D8-D13	Rectifier	1600 V	25 A	Rectifier Diode	
T1-T6	IGBT	1200 V	15 A	Inverter Switch	
D1-D6	FWD	1200 V	15 A	Inverter Diode	
T7	IGBT	1200 V	15 A	Brake Switch	
D7	FWD	1200 V	15 A	Brake Diode	
PTC1	PTC			Thermistor	



Packaging instruction			
Standard packaging quantity (SPQ)	120	>SPQ Standard	<SPQ Sample

Handling instruction
Handling instructions for MiniSkiiP [®] 1 packages see vincotech.com website.

Package data
Package data for MiniSkiiP [®] 1 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
V23990-K200-A40-D7-14	12 Feb. 2018		

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.